



CSOD400XSF Series

1.0Amp. Surface Mount Glass Passivated Type Rectifiers

Features

- For surface mounted application
- Low forward voltage drop
- High current capability
- Easy pick and place
- Low leakage current
- Plastic material used carries Underwriters Laboratory Flammability Classification 94V-0 Utilizing Flame Retardant Epoxy Molding Compound.
- High temperature soldering: 250°C/10 seconds at terminals
- Exceeds environmental standards of MIL-S-19500/228

Mechanical Data

- Case: Molded Plastic , JEDEC SOD-123 / mini-SMA.
- Terminals: Solder plated. Solderable per MIL-STD-750 Method 2026
- Polarity: Indicated by cathode band.
- Mounting Position: Any.
- Weight: 0.04 gram

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

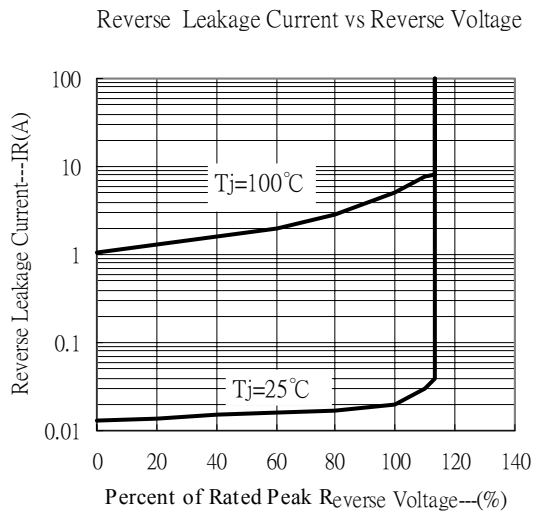
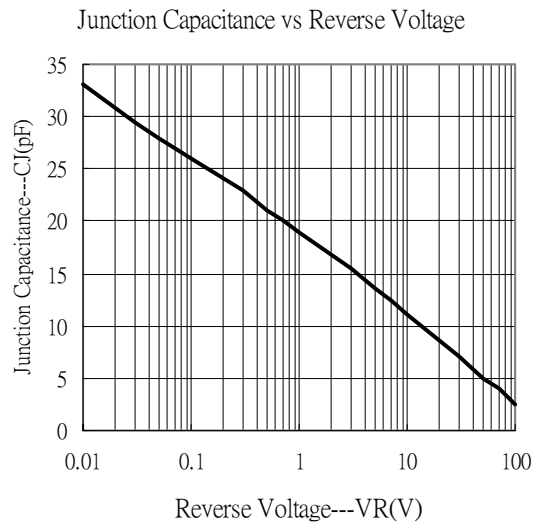
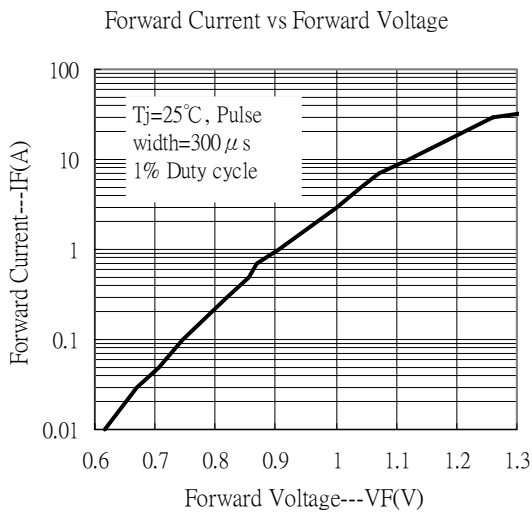
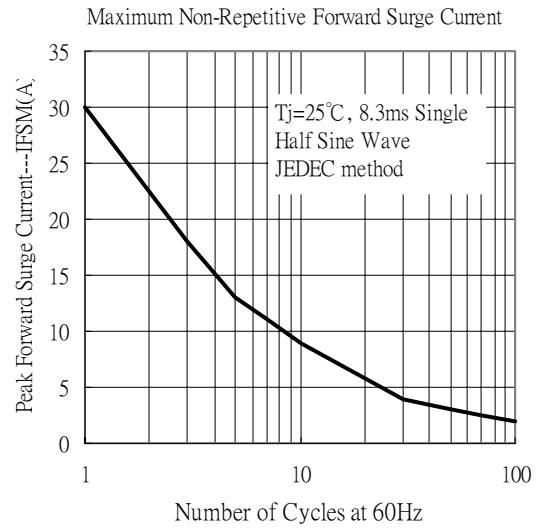
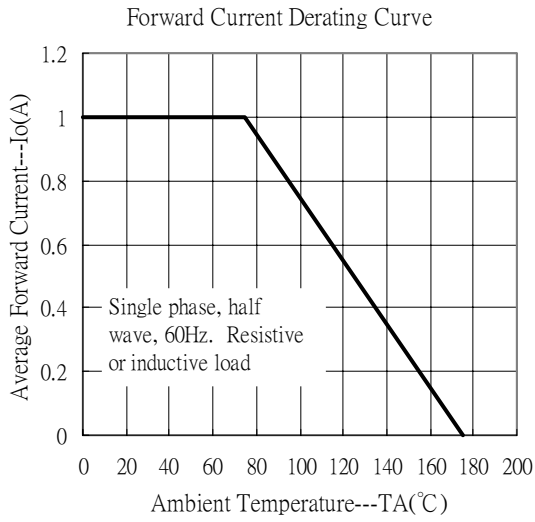
Type Number	CSOD 4001	CSOD 4002	CSOD 4003	CSOD 4004	CSOD 4005	CSOD 4006	CSOD 4007	Units
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	1							A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load(JEDEC method)	30							A
Maximum Instantaneous Forward Voltage @ 1.0A	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	5(@Ta=25°C) 50(@Ta=100°C)							µA
Maximum Reverse Recovery Time (Note 1)	1.8							µs
Thermal Resistance, Junction to Ambient	60							°C/W
Typical Junction Capacitance (Note 2)	15							pF
Operating Temperature Range Tj	-55 to +150							°C
Storage Temperature Range Tstg	-55 to +150							°C

Note1: Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, IRR=0.25A

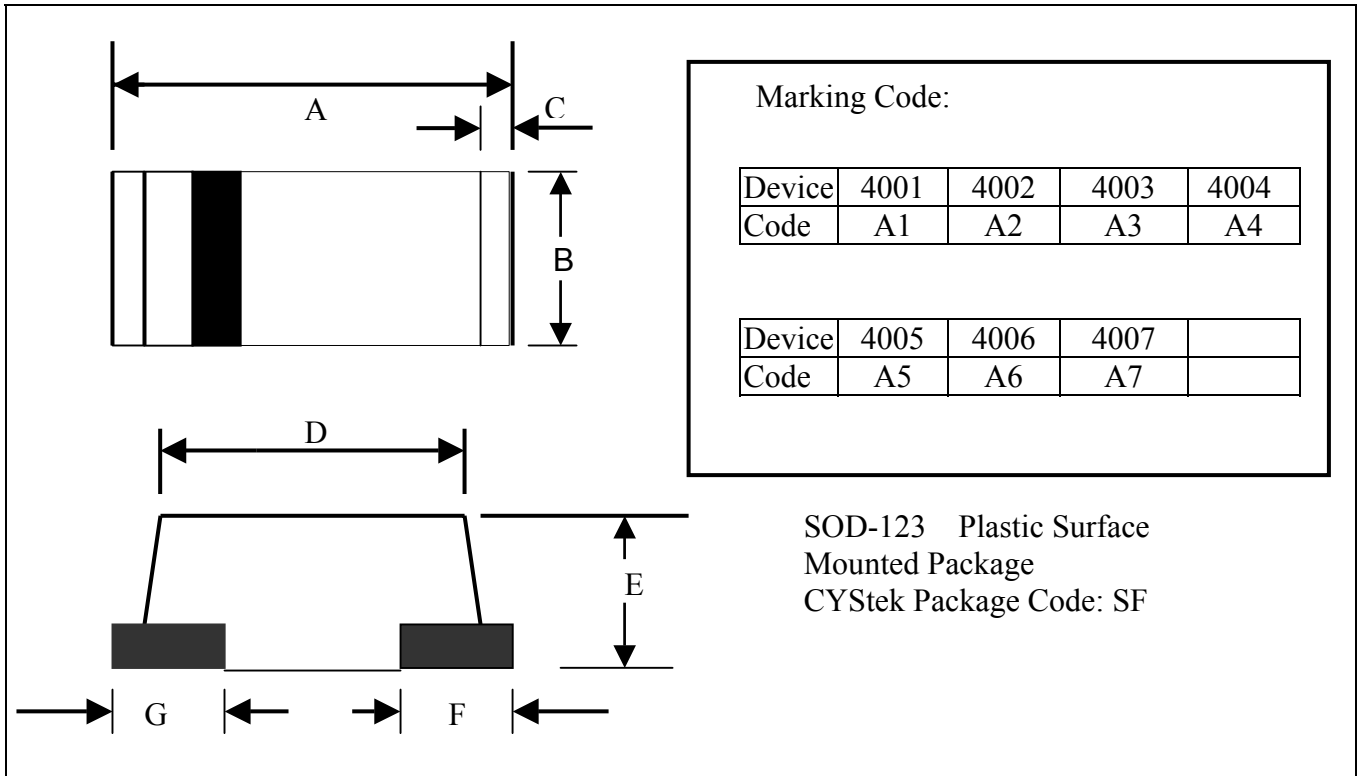
Note2: Measured at 1 MHz and Applied VR=4.0Volts



Characteristic Curves



SOD-123 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.146	0.161	3.7	4.1	E	0.055	0.063	1.4	1.6
B	0.055	0.071	1.4	1.8	F	0.035(typ)		0.9(typ)	
C	0.012(typ)		0.3(typ)		G	0.035(typ)		0.9(typ)	
D	0.094	0.110	2.4	2.8	-	-	-	-	-

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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